

(19) World Intellectual Property Organization  
International Bureau



(43) International Publication Date  
25 January 2007 (25.01.2007)

PCT

(10) International Publication Number  
**WO 2007/011313 A1**

(51) International Patent Classification:

C08K 7/00 (2006.01) C08K 7/02 (2006.01)  
C08K 3/04 (2006.01) C08K 13/00 (2006.01)  
C08K 3/34 (2006.01) C08L 63/00 (2006.01)

(21) International Application Number:

PCT/SG2006/000204

(22) International Filing Date: 20 July 2006 (20.07.2006)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

60/700,974 20 July 2005 (20.07.2005) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

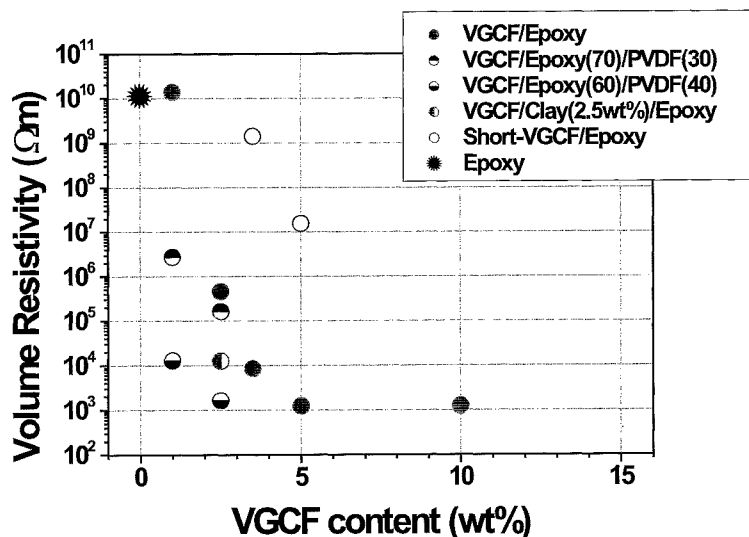
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— with international search report

[Continued on next page]

(54) Title: ELECTROCONDUCTIVE CURABLE RESINS



(57) Abstract: An electroconductive polymer composition comprises a curable liquid thermosetting resin matrix; conductive nano-fibres such as carbon nano-tubes, carbon nano-fibres, metallic nano-fibres or non-conductive nano-fibres with an electrically conductive coating; and a particulate non-conductive phase discontinuously dispersed throughout the thermosetting matrix. The conductive nano-particles are dispersed throughout the matrix whereby when the thermosetting resin is cured, a percolation threshold is established within the thermoset matrix. The particulate non-conductive phase is selected from thermoplastic resin powders or exfoliated particles of nano-clay intercalated with the liquid thermosetting resin.

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